

AMENDMENTS TO THE SPECIFICATION:

Please replace the paragraph beginning at page 15, line 7, with the following rewritten paragraph:

1 The flip chip assembly using radiant heating advantageously is a reel to
2 reel process as illustrated in Figure 7. From a reel 70, a patterned flexible film
3 substrate 72 is indexed to a paste dispense work station 73 where a
4 thermosetting ~~non-thermosetting~~ adhesive paste 731 is deposited onto the
5 center of the each device substrate 72. At the next in-line position 74, a bumped
6 chip 71 is aligned to substrate contact pads and is thermal compression bonded
7 within a matter of seconds. The assemblage is indexed to the IR cure station 75
8 where the adhesive 731 is gelled and at least partially cured, prior to moving to
9 the take-up reel 80. The reel loaded with assembled devices may then be taken
10 to an off-line convection cure system for completing cross-linking and stress
11 relief of the assembled devices in reel format.